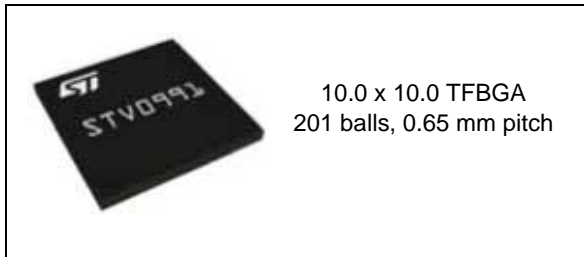


Versatile imaging processor

Data brief



Features

- Self-contained, no external memory needed
 - Central system
 - ARM® Cortex-R4 CPU @500 MHz
 - 2 Mbytes of SRAM
 - 4 Mbytes of stacked Flash or 16 Mbyte external Flash with update via communication interfaces
 - emulated EEPROM
 - interrupt and DMA controllers
 - HDR on-the-fly image signal processing
 - 150 Mpixel/s effective throughput, up to 5 Mpixel and 22 bit front-end processing
 - global tone mapping
 - lens shading correction noise suppression, defective pixel repair, sharpening, adaptive color matrix, multiple scaling engines
 - image statistics engine for AEC/AWB
 - Video compression
 - JPEG 8-bit/12-bit, 5/2.1 Mpixel @30 fps
 - H.264 baseline I,P, 2.1 Mpixel @30 fps
 - Video analytics accelerators
 - edge data extractor
 - optical flow generator
 - Lens distortion (for example fish-eye) correction
 - Graphics overlay
 - Code protection against hacking
- Multi-camera synchronization support
 - Operation with quartz crystal or external clock
 - Interfaces
 - Serial (CSI-2) input
 - Parallel video input and output
 - RGMII/GMII, 2x SDIO, 2x SPI, 3x I²C, CAN, 6x LIN, multiple GPIOs with 4x ADC inputs
 - I²S in, I²S out, PDM for digital microphone
 - clock output for image sensor
 - ASIL-related features
 - Low power consumption
 - -40 °C to +105 °C operating temperature range (T_a)
 - AEC-Q100 grade 2 compliance

Applications

- Automotive: multi-camera systems, stand-alone rear-view smart cameras, video chat, driver monitoring, AVin-to-Ethernet bridge, black-box system
- Security/building management: energy saving, smart sensors, video surveillance IP cameras, intruder alarm detector units, public lighting smart sensor etc.
- Consumer/residential IP cameras, video chat encoding cameras, sports cameras.

Contents

1	Description	5
2	Technical specifications	6
3	Block diagram	8
4	Package information	9
	4.1 TFBGA 201 10x10x1.12 package information	9
5	Ordering codes	11
6	Revision history	12

List of tables

Table 1.	STV0991 technical specifications	6
Table 2.	TFBGA201 package dimensions	10
Table 3.	Ordering codes	11
Table 4.	Document revision history	12

List of figures

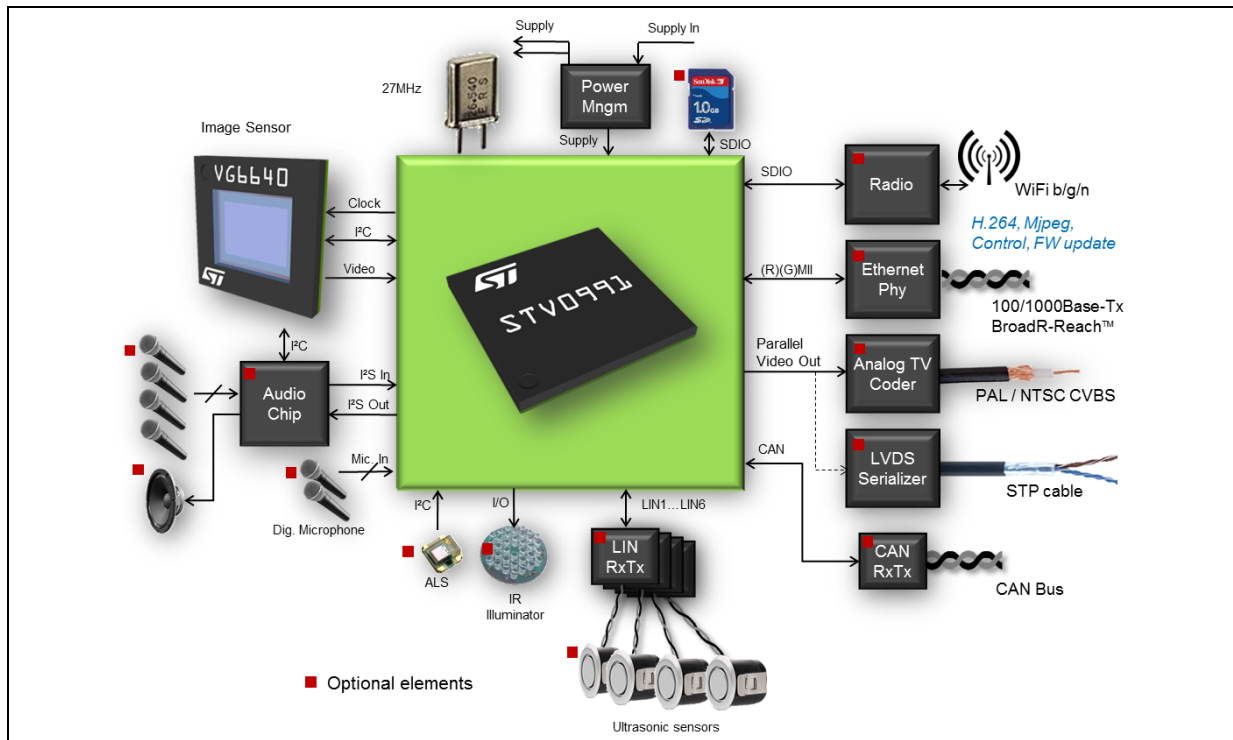
Figure 1.	STV0991 application diagram.	5
Figure 2.	STV0991 block diagram	8
Figure 3.	TFBGA 201 10x10x1.12 package outline.	9

1 Description

The STV0991 is a versatile system-on-chip device designed for automotive, security and a multitude of other camera applications. From video and audio input through HDR image signal processing, lens distortion correction, graphics overlay, video compression, video analytics acceleration, CPU, operating and non-volatile memory, media access controller, to video and audio outputs and communication interfaces, it comprises all elements to support compact, low bill-of-material and low energy-consumption camera applications. No external memory chips such as DRAM or Flash are required for its operation, predictive H.264 video encoding inclusive.

Video analytics accelerators unload the central CPU from intensive repetitive tasks. A graphics renderer unit compensates for perceptual distortion produced by wide-angle lenses (such as fish-eye) and inserts graphical and/or textual information over the video. Resulting ready-for-display video can be output as-is over the parallel or serial video output port, or real-time compressed for streaming out through one of: RGMII/GMII, SDIO or SPI interfaces. An audio signal can be input through either an I²S or a PDM input, processed by the CPU and inserted into the output data stream. A return audio channel is also supported, outputting the audio on an I²S output. Precise Time Protocol (PTP) support and other provisions on the die allow precise instant-of-exposure synchronization of cameras in a multi-camera system, independent of cable lengths. A cryptographic and hash unit permits protection of customer intellectual property embedded in their software. Flash content can be updated via communication interfaces, thus allowing non-intrusive customer firmware updates. A debug access port (DAP) helps users in their software development process. The application diagram in *Figure 1* suggests some of the applications possible through combining optional elements as required.

Figure 1. STV0991 application diagram



2 Technical specifications

Table 1. STV0991 technical specifications

Function	Value or Detail
CPU	ARM® Cortex™-R4 (ARM® V7 architecture)
Clock frequency	500 MHz maximum
Interconnect	High-throughput AXI: 64 bit data bus size at 250 MHz
Caches	L1: 32 Kbyte instruction, 32 Kbyte data, L2: 128 Kbyte L2
Interrupt controller	Vectored
DMA controller	Multi-channel general-purpose
System volatile memory	2 Mbytes SRAM with programmable allocation and DMA channel
Flash (STV0991Fx)	4 Mbytes serial Flash with 4 data lines
EEPROM (STV0991Fx)	Emulated with Flash memory (actual size depends on allocated Flash area, restrictions apply)
ISP throughput and resolution	150 Mpixel/s effective throughput, 5 Mpixel maximum spatial resolution
ISP pipe data bit depth	22 bit image reconstruction, 14-bit processing, 12-bit and 2 x 8-bit outputs
ISP scaling capabilities	Up-scaling to 4x max., down-scaling to 16x max., programmable
H.264 video compressor	Baseline 4.1, 75 Mpixel/s throughput, 2.1 Mpixel max; I,P; Low latency support
JPEG video compressor	Baseline 8 bit / 12 bit; YUV 422/420; Max resolution 5 Mpixel in 8-bit mode and 2.1 Mpixel in 12-bit mode.
Video analytics operating resolution	Maximum 640 x 480 pixel, scaled or/and cropped from image sensor resolution
Edge extraction method	Gradient maxima search, gradient continuity search with ID labelling
Edge extraction ROI number	6 regions of interest, overlap allowed
Edge ext.output data per edge point	Coordinates, Edge ID, DMA channel
Feature extraction method	N-cornerness, signature of gradient distribution around the point
Number of extracted Feature points	4k maximum, limited by dedicated feature point buffer sizes
Feature point density control	Closed loop varying detection threshold, area-based rejection of lowest cornerness points
Optical flow generation method	"difference of signature" in a search region, for subsequent frames
Optical flow output data per vector	Origin, tip delta-coordinates and matching distance of best-matched feature. Matching distance of second best-matched feature.
Lens distortion correction method	Combination of affine, radial and perspective transforms
Amount of lens distortion correction	Horizontal over 100%, Vertical 60% (VGA), 20% (HD), 9% (Full-HD)
Graphics Overlay general properties	290 Mpixel/s throughput, 16 x 16 pixel tile-based rendering
Graphics Overlay source properties	8-bit pixel transparency, true color, YUV or RGB with versatile planariness
Graphics Overlay layer properties	Affine, radial and perspective transform, 8-bit transparency
Graphics overlay layer number	Up to 7 layers, with independent rendering properties, blended onto an extra layer used for video rendering (lens mapping correction).
Serial video input port type	D-PHY/CSI-2 (MIPI) dual-lane
Serial video port data depth/speed	12-bit max./ 1 Gbit/s max. per lane, total 2 Gbit/s max. (input)

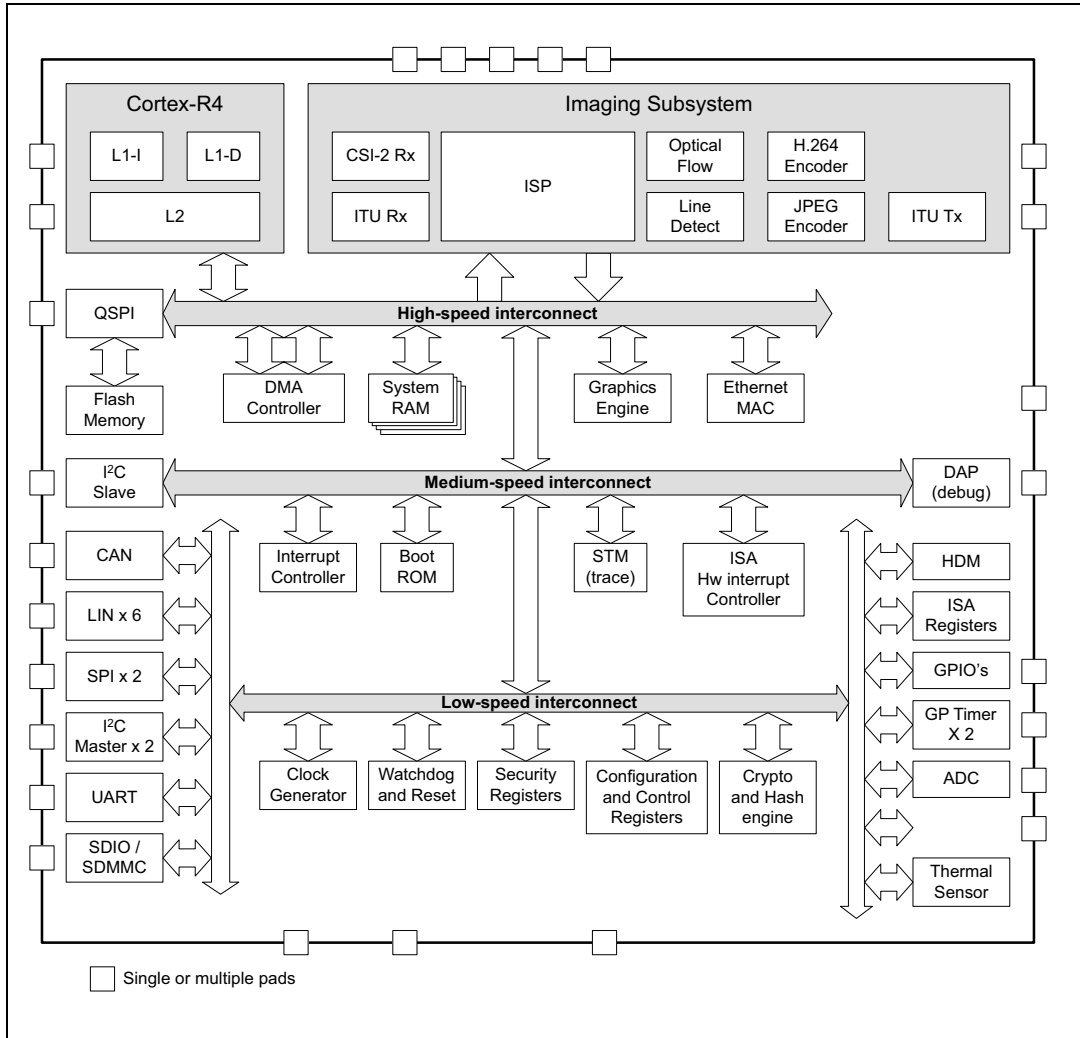
Table 1. STV0991 technical specifications (continued)

Function	Value or Detail
Parallel video input port width	16 data lines max., pixel clock, Hsync, Vsync, embedded sync. support
Parallel video input formats	YCbCr on 8/10/12/16 data lines, (incl. BT.601/656), RGB565 and RGB888 on 16 data lines (transparent mode for RGB data)
Parallel video output port width	16 data lines max., Pixel clock, Hsync, Vsync, embedded sync. support
Parallel video output formats	YCbCr on 8/10/12/16 data lines (incl. BT.601/656), RGB565 and RGB888 on 16 data lines (transparent mode for RGB data)
Parallel video input port clock speed	120 MHz at 1.8 V, 80 MHz at 3.3 V
Parallel video output port clock speed	120 MHz at 1.8 V, 80 MHz at 3.3 V
Ethernet MAC operating modes	Fast Ethernet controller, Gigabit Ethernet controller
Ethernet MAC supported interfaces	MII, RMII, GMII, RGMII
Ethernet MAC real-time support	IEEE802.1 (AVB), including IEEE802.1AS (PTP)
(R)(G)MII operating voltage modes	1.8 V, 3.3 V
I ² C interface operating modes	1.8 V, 3.3 V, 100 kHz, 400 kHz, 1 MHz, both master (2x) and slave (1x)
SPI interface operating modes	1.8 V, 3.3 V, slave up to 10.4 Mbit/s, master up to 25 Mbit/s, DMA channel, 6 x CS
GPIO operating modes	1.8 V (100 MHz max.), 3.3 V (60 MHz max.); 4 mA drive
I ² S interface	1.8 V, 3.3 V, max. 48 kHz sampling, max. 24-bit sample, TDM supported
SD Card interface (SDIO controller)	3.3 V, Class 6, 48 Mbit/s max., 2 Tbyte max., SD/SDHC/SDXC
WiFi radio interface (SDIO controller)	3.3 V, High-speed and Low-speed support
Serial Flash Interface	1.8 V and 3.3 V modes, max.104 MHz clock, 4 data lines
Automotive Safety Integrity Level	Temperature sensor, PEC on some memories, WDT, Sensor status lines extractor and interpreter
Supply voltages	1.1 V for digital processing (required) 1.8 V / 3.3 V for I/Os (at least one of the voltage levels required) 1.2 V for CSI-2 interfaces (required if CSI-2 used) 2.5 V for analog circuitry (required)
Operating temperature range (Tj)	-40 °C to +125 °C
Storage temperature range (Tstg)	-40 °C to +150 °C
Package	TFBGA 10.0 mm x 10.0 mm, 0.65 mm ball pitch, 201 balls
External clock frequency range	6 to 27 MHz, AC or DC coupled

3 Block diagram

Figure 2 shows the schematic block diagram of the STV0991. Functional blocks are interconnected via high-speed, medium-speed and low-speed buses so as to optimize the device architecture for performance, silicon size and power consumption.

Figure 2. STV0991 block diagram



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

4.1 TFBGA 201 10x10x1.12 package information

Figure 3. TFBGA 201 10x10x1.12 package outline

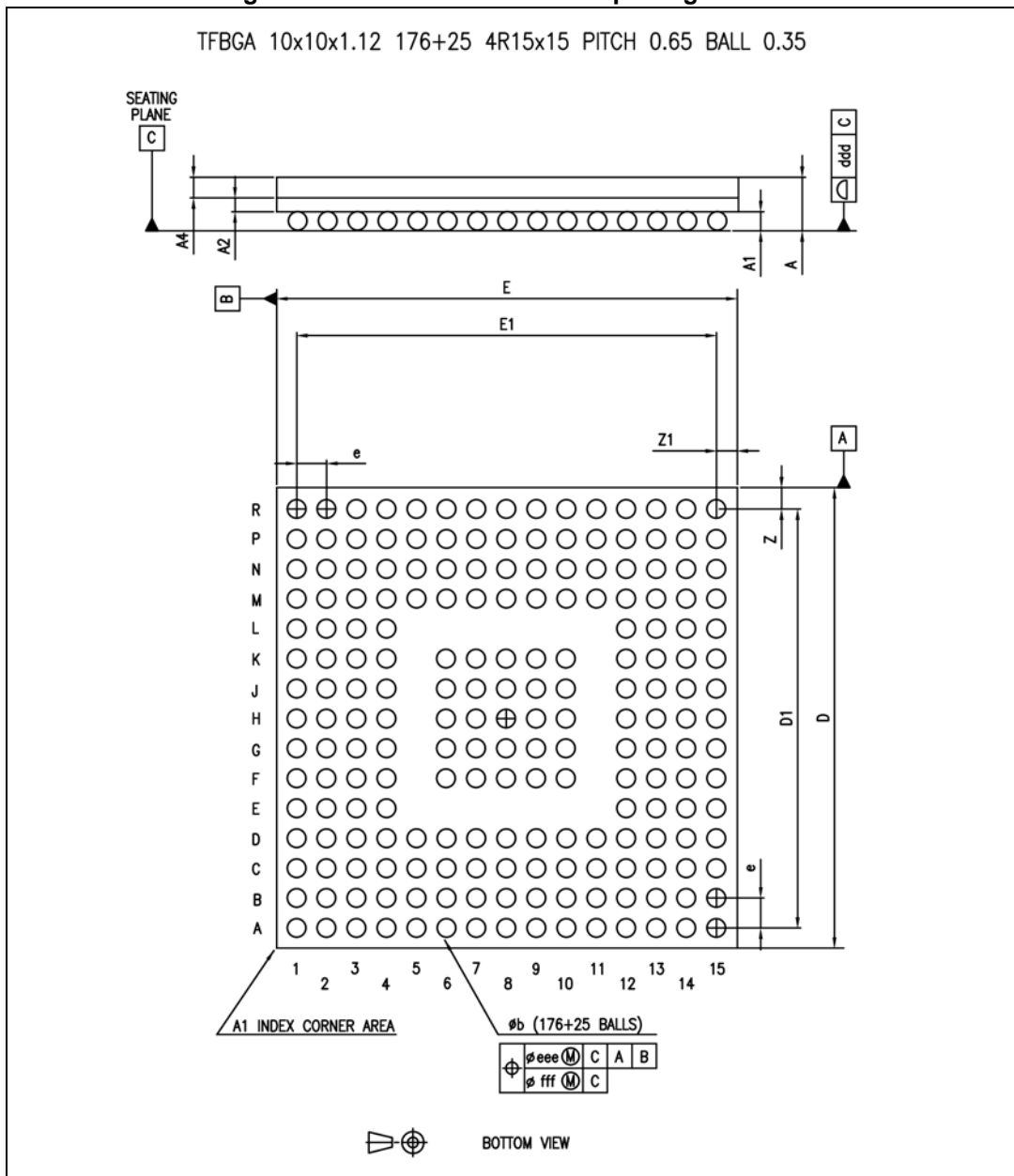


Table 2. TFBGA201 package dimensions

Ref.	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A ⁽²⁾			1.12			0.0441
A1 ⁽³⁾	0.22	0.27	0.32	0.0087	0.0106	0.0126
A2 ⁽⁴⁾	0.16	0.20	0.24	0.0063	0.0079	0.0094
A4 ⁽⁵⁾	0.57	0.585	0.60	0.0224	0.0230	0.0236
b ⁽⁶⁾	0.30	0.35	0.40	0.0118	0.0138	0.0157
D	9.95	10	10.05	0.3898	0.3937	0.3976
D1		9.1			0.3583	
E	9.95	10.0	10.05	0.3898	0.3937	0.3976
E1		9.1			0.3583	
e ⁽⁷⁾		0.65			0.0256	
Z		0.45			0.0177	
Z1		0.45			0.0177	
ddd			0.10			0.0039
eee			0.15			0.0059
fff			0.08			0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits
2. Total thickness
3. Stand Off
4. 2ML Substrate
5. Molding
6. Ball size
7. Pitch

5 Ordering codes

Table 3. Ordering codes

Part number⁽¹⁾	Description
STV0991FAH	4 Mbyte Flash, automotive, tray
STV0991FAH/TR	4 Mbyte Flash, automotive, tape & reel

1. All versions are in 10.0 x 10.0 TFBGA package

6 Revision history

Table 4. Document revision history

Date	Revision	Changes
17-Jul-2012	1	Initial release.
09-Oct-2012	2	Spatial resolution modified, text edits
01-Aug-2013	3	Update of ordering codes, removal of redundant information, update of some parameters
25-Nov-2013	4	Alignment with Datasheet v05
04-Feb-2014	5	Correct typo error (STV0991N instead of STV0991G) Add ECOPACK [®] section Modify section ordering, Revision history et the end of the data-brief
07-Mar-2014	6	Update – Table 1 Add: – Table 1 , Table 3 , Table 4
07-Oct-2015	7	Alignment with data-sheet rev 7.0 Typo corrections Improved descriptions and added storage temperature in technical specifications table Added package outline and mechanical data Modified sections ordering
26-Feb-2016	8	Removed previous Table 1: Device summary from cover page. Corrected Table 2: TFBGA201 package dimensions Added 4 Mbyte Flash to: – cover page features – Table 1: STV0991 technical specifications Added STV0991FAH(/TR) to: – Table 1: Device summary – Table 3: Ordering codes Added STV0991FAH to Table 4: Feature set differences
04-Oct-2018	9	Updated Features in cover page. Updated Table 1: STV0991 technical specifications . Minor text changes

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved